

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JUNICHI KOIKE	12/01/2016
YUJI SUTOU	12/01/2016
DAISUKE ANDO	12/01/2016
RECEIVING PARTY DATA	
Name:	MATERIAL CONCEPT, INC.
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Internal Address:	ARAMAKI, AOBA-KU
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State/Country:	JAPAN
Postal Code:	9800845
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15319549
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SIGNATURE:	/Daniel P. Lent/
DATE SIGNED:	12/19/2016
Total Attachments: 2	
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ASSIGNMENT

WHEREAS We, Junichi KOIKE, Yuji SUTOU, and Daisuke ANDO c/o Material Concept, Inc., 6-6-40-408 Aza-Aoba, Aramaki, Aoba-ku, Sendai-shi, Miyagi, Japan, 9800845, (hereinafter referred to as "ASSIGNORS") have invented certain new and useful improvements in:

METHOD FOR FIRING COPPER PASTE

which claims priority to Japanese Application No. 2014-123799, filed June 16, 2014, and for which I am about to file or have filed an application for Letters Patent of the United States;

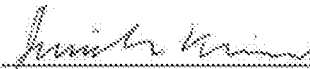
AND WHEREAS, Material Concept, Inc. (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Japan, having a place of business at 6-6-40-408 Aza-Aoba, Aramaki, Aoba-ku, Sendai-shi, Miyagi Japan, 9800845, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention, the applications, and any and all patents that may be issued therefrom, in the United States and in all foreign countries, including any and all revivals, refilings, continuations, continuations-in part, divisions, and reissues thereof, to the said ASSIGNEE; and we, the ASSIGNORS, do hereby agree that we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

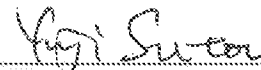
The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like

so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

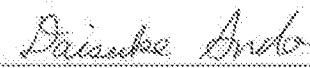
Date: December 1, 2016


Junichi KOIKE

Date: December 1, 2016


Yaji SUTOU

Date: December 1, 2016


Daisuke ANDO